

■ India, Japan Sign MoU to Develop Resilient Semiconductor Supply Chain



India and Japan have signed a Memorandum of Understanding (MoU) to develop a resilient semiconductor supply chain. Recognising Japan's prominence as a semiconductor producer and technology developer, India has sought collaboration in manufacturing, equipment research, design, talent development, and supply of semiconductors. Electronics and IT Minister Shri Ashwini Vaishnaw highlighted India's rapid progress in its semiconductor mission while emphasizing that the MoU signifies the global confidence in India's capabilities and dedication to establishing a comprehensive semiconductor ecosystem within the country.

Additionally, India and Japan are also exploring cooperation in decarbonisation of the steel sector. Steel Minister Shri Jyotiraditya Scindia and Japan's Minister of Economy, Trade, and Industry Mr. Nishimura Yasutoshi met in New Delhi on July 20 to discuss the matter. India and Japan, being the world's second and third-largest steel producers, acknowledge the significance of collaboration to achieve their respective net-zero goals, taking into account the diverse pathways towards steel decarbonisation.